

## NOTES:

- MATERIAL:  
1-1 HOUSING: LCP, 30% G/F, UL 94V-0, BLACK  
1-2 SIGNAL TERMINAL AND DETECT TERMINAL: PHOSPHOR BRONZE  
1-3 METAL SHELL: STAINLESS STEEL
- FINISH:  
2-1 SIGNAL TERMINAL: 1.25 MICRON NICKEL MIN UNDER-PLATED,  
CONTACT AREA SEE TABLE, GOLD FLASH ON SOLDER AREA.  
2-2 METAL SHELL: GOLD FLASH PLATED OVER NICKEL ON SOLDER AREA.  
2-3 DETECT PIN: 1.25 MICRON NICKEL MIN UNDER-PLATED,  
GOLD FLASH ON CONTACT AREA, TIN PLATED ON SOLDER AREA.
- PRODUCT COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV 2000/53/EC.

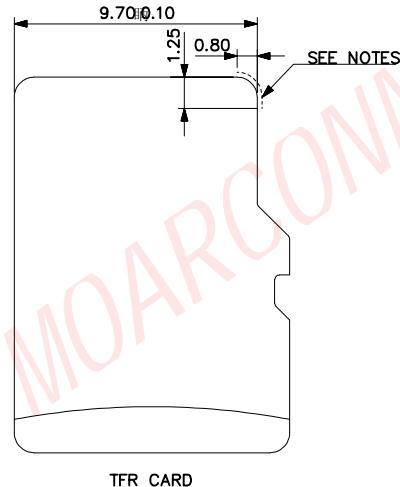
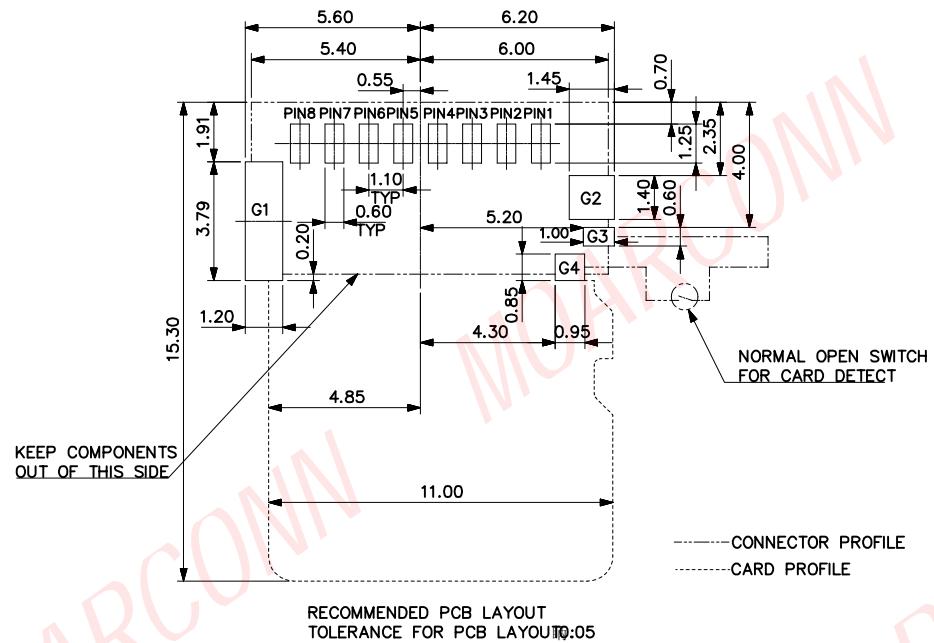
**MOARCONN®**  
More Connections Smart Future

DONG GUAN MOARCONN ELECTRONIC Co., Ltd.

X0	-----	NEW RELEASE	Aaron	2024.11.09
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
1	2	3	4	5

DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE	PRODUCT NAME : Micro SD H2.65 SMT Card	DRAWING: Zhangli	DATE: 2025.1.4
DIMENSION TOLERANCE	PRODUCT NO. : MC265-T1151-01-W	CHECK: /	DATE: /
X.X: ± 0.10 X.XX: ± 0.05 X.XXX: ± 0.02 ANGULAR: ± 1°	DRAWING NO. : D-MC265-T1151-01-W	APPROVED:	DATE:
SCALE: 1:1	DWG ID: P D	REV.: X0	PAGE: 1 OF 2

All materials, plating and process meet HF requirements.



NOTES:  
NO CONDUCTIVE EXPOSURE TRACE IS ALLOWED ON THE SIDE FACE

G4	DET
G3	POL
G2	GND
G1	GND
P8	DAT1
P7	DAT0
P6	VSS
P5	CLK
P4	VDD
P3	CMD
P2	CD/DAT3
P1	DAT2
NAME	TYPE
PIN ASSIGNMENT	

X0	-----	NEW RELEASE	Aaron	2024.11.09
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE

**MOARCONN®**  
More Connections Smart Future

DIMENSIONS INIT: mm  
UNLESS OTHERWISE SPECIFIABLE  
DIMENSION TOLERANCE  
X.X: ± 0.10  
X.XX: ± 0.05  
X.XXX: ± 0.02  
ANGULAR: ± 1°

PRODUCT NAME :	Micro SD H2.65 SMT Card	DRAWING:	Zhangli	DATE:	2025.1.4
PRODUCT NO. :	MC265-T1151-01-W	CHECK:	/	DATE:	/
DRAWING NO. :	D-MC265-T1151-01-W	APPROVED:		DATE:	
SCALE:	1:1	DWG ID:	P D	REV.:	X0
PAGE:	2 OF 2				